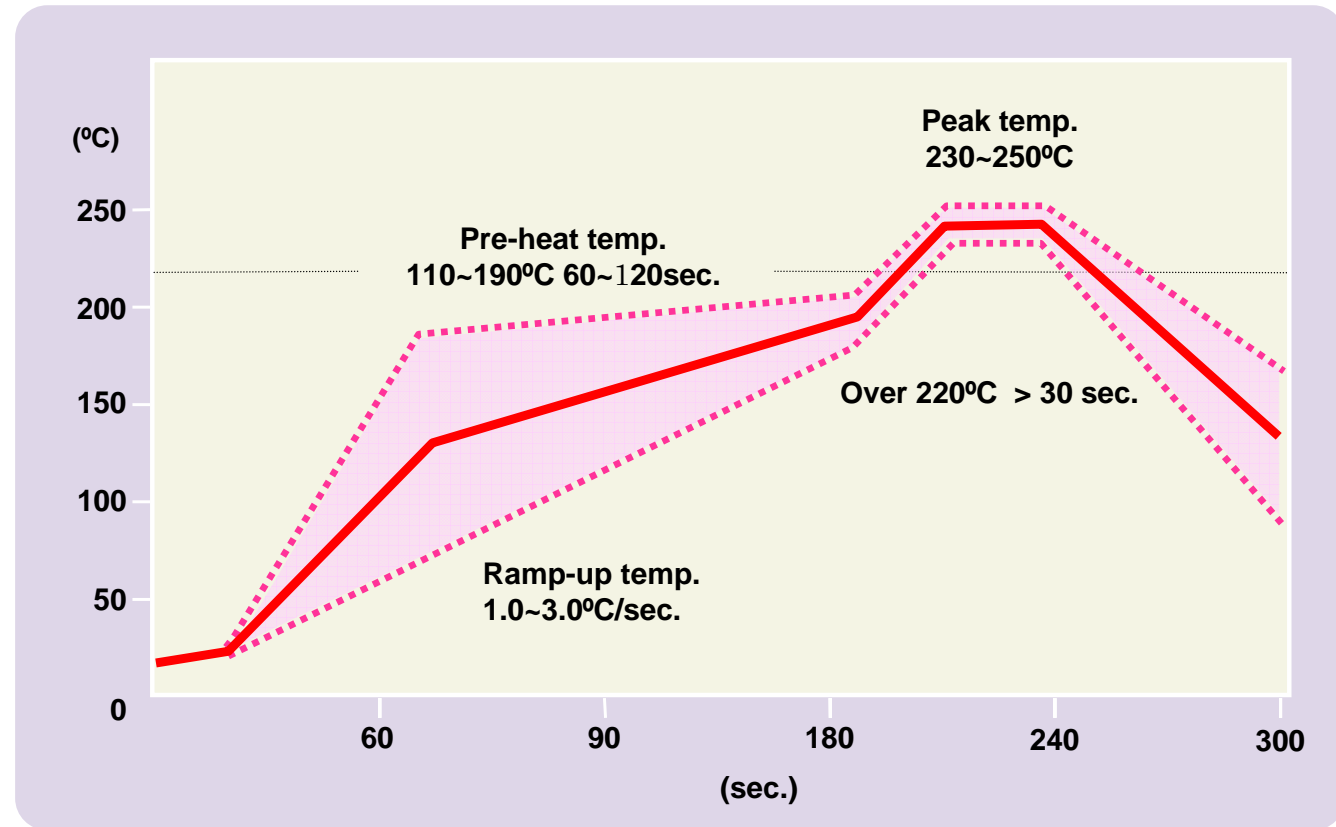


TopLine Sn Ag Cu Lead Free

BGA & CSP Recommended reflow profile



Excess pre-heating (time & temperature) may cause too much oxidation.

Relatively short and low pre-heat may be recommendable, especially for fine pitch/micro pattern components .

Bake parts at 125°C for 24 hours prior to use. Actual Results Might be Different. No Guarantee is made.